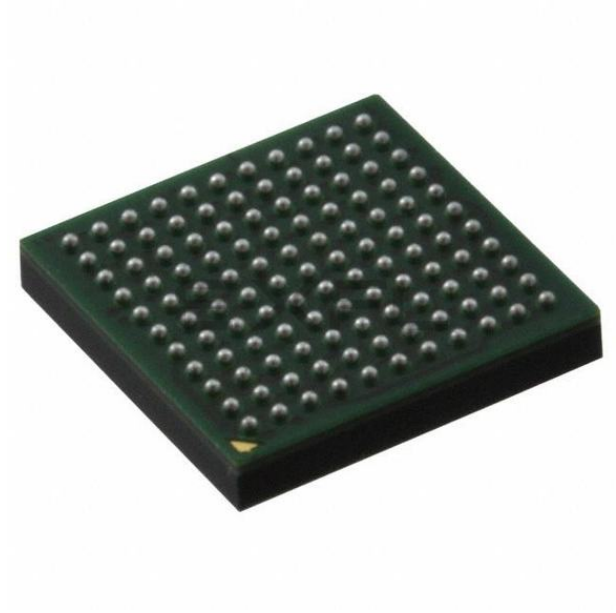

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	I²C, IrDA, SPI, UART/USART, USB, USB OTG
Peripherals	DMA, I²S, LVD, POR, PWM, WDT
Number of I/O	67
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 34x16b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	121-XFBGA
Supplier Device Package	121-BGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mk22fn128vdc10

Table 2. V_{DD} supply LVD and POR operating requirements (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	Low-voltage warning thresholds — high range					1
V_{LVW1H}	• Level 1 falling (LVWV=00)	2.62	2.70	2.78	V	
V_{LVW2H}	• Level 2 falling (LVWV=01)	2.72	2.80	2.88	V	
V_{LVW3H}	• Level 3 falling (LVWV=10)	2.82	2.90	2.98	V	
V_{LVW4H}	• Level 4 falling (LVWV=11)	2.92	3.00	3.08	V	
V_{HYSH}	Low-voltage inhibit reset/recover hysteresis — high range	—	80	—	mV	
V_{LVDL}	Falling low-voltage detect threshold — low range (LVDV=00)	1.54	1.60	1.66	V	
	Low-voltage warning thresholds — low range					1
V_{LVW1L}	• Level 1 falling (LVWV=00)	1.74	1.80	1.86	V	
V_{LVW2L}	• Level 2 falling (LVWV=01)	1.84	1.90	1.96	V	
V_{LVW3L}	• Level 3 falling (LVWV=10)	1.94	2.00	2.06	V	
V_{LVW4L}	• Level 4 falling (LVWV=11)	2.04	2.10	2.16	V	
V_{HYSL}	Low-voltage inhibit reset/recover hysteresis — low range	—	60	—	mV	
V_{BG}	Bandgap voltage reference	0.97	1.00	1.03	V	
t_{LPO}	Internal low power oscillator period — factory trimmed	900	1000	1100	µs	

1. Rising threshold is the sum of falling threshold and hysteresis voltage

Table 3. VBAT power operating requirements

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{POR_VBAT}	Falling VBAT supply POR detect voltage	0.8	1.1	1.5	V	

2.2.3 Voltage and current operating behaviors

Table 4. Voltage and current operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{OH}	Output high voltage — Normal drive pad except RESET_B					
	2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = -5 mA	V_{DD} – 0.5	—	—	V	1
	1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OH} = -2.5 mA	V_{DD} – 0.5	—	—	V	
V_{OH}	Output high voltage — High drive pad except RESET_B					
	2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = -20 mA	V_{DD} – 0.5	—	—	V	1

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	@ 1.8V	—	19.51	20.24	mA	2, 3, 4
	@ 3.0V	—	19.51	20.24	mA	
I_{DD_HSRUN}	High Speed Run mode current - all peripheral clocks disabled, code executing from flash					
	@ 1.8V	—	16.9	17.63	mA	5
	@ 3.0V	—	17.0	17.73	mA	
I_{DD_HSRUN}	High Speed Run mode current — all peripheral clocks enabled, code executing from flash					
	@ 1.8V	—	22.8	23.53	mA	6
	@ 3.0V	—	22.9	23.63	mA	
I_{DD_RUN}	Run mode current in Compute operation — CoreMark benchmark code executing from flash					
	@ 1.8V	—	11.39	12.12	mA	2, 3, 7
	@ 3.0V	—	11.58	12.31	mA	
I_{DD_RUN}	Run mode current in Compute operation — code executing from flash					
	@ 1.8V	—	10.90	11.90	mA	7
	@ 3.0V	—	10.90	12.23	mA	
I_{DD_RUN}	Run mode current — all peripheral clocks disabled, code executing from flash					
	@ 1.8V	—	11.8	12.53	mA	8
	@ 3.0V	—	11.9	12.63	mA	
I_{DD_RUN}	Run mode current — all peripheral clocks enabled, code executing from flash					
	@ 1.8V	—	15.5	16.23	mA	9
	@ 3.0V					
	• @ 25°C	—	15.6	16.33	mA	
	• @ 70°C	—	15.6	16.33	mA	
	• @ 85°C	—	15.6	16.33	mA	
	• @ 105°C	—	16.3	17.03	mA	
I_{DD_RUN}	Run mode current — Compute operation, code executing from flash					
	@ 1.8V	—	10.9	11.63	mA	10
	@ 3.0V					
	• @ 25°C	—	10.9	11.63	mA	
	• @ 70°C	—	10.9	11.63	mA	
	• @ 85°C	—	10.9	11.63	mA	
	• @ 105°C	—	11.5	12.23	mA	

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I_{DD_WAIT}	Wait mode high frequency current at 3.0 V — all peripheral clocks disabled	—	6.5	7.23	mA	8
I_{DD_WAIT}	Wait mode reduced frequency current at 3.0 V — all peripheral clocks disabled	—	3.9	4.63	mA	11
I_{DD_VLPR}	Very-low-power run mode current in Compute operation — CoreMark benchmark code executing from flash					
	@ 1.8V	—	0.60	0.88	mA	2, 3, 12
	@ 3.0V	—	0.61	0.89	mA	
I_{DD_VLPR}	Very-low-power run mode current in Compute operation, code executing from flash					
	@ 1.8V	—	0.48	0.76	mA	12
	@ 3.0V	—	0.48	0.76	mA	
I_{DD_VLPR}	Very-low-power run mode current at 3.0 V — all peripheral clocks disabled	—	0.54	0.82	mA	13
I_{DD_VLPR}	Very-low-power run mode current at 3.0 V — all peripheral clocks enabled	—	0.79	1.07	mA	14
I_{DD_VLPW}	Very-low-power wait mode current at 3.0 V — all peripheral clocks disabled	—	0.30	0.59	mA	15
I_{DD_STOP}	Stop mode current at 3.0 V					
	@ -40°C to 25°C	—	0.27	0.33	mA	
	@ 70°C	—	0.31	0.36	mA	
	@ 85°C	—	0.31	0.36	mA	
	@ 105°C	—	0.43	0.66	mA	
I_{DD_VLPS}	Very-low-power stop mode current at 3.0 V					
	@ -40°C to 25°C	—	4.2	9.00	µA	
	@ 70°C	—	15.8	31.90	µA	
	@ 85°C	—	26.9	50.95	µA	
	@ 105°C	—	43.0	89.00	µA	
I_{DD_LLS3}	Low leakage stop mode 3 current at 3.0 V					
	@ -40°C to 25°C	—	2.6	3.30	µA	
	@ 70°C	—	6.2	8.60	µA	
	@ 85°C	—	9.6	12.30	µA	
	@ 105°C	—	15.0	26.00	µA	
I_{DD_LLS2}	Low leakage stop mode 2 current at 3.0 V					
	@ -40°C to 25°C	—	2.4	3.00	µA	
	@ 70°C	—	5.2	6.85	µA	
	@ 85°C	—	7.9	9.95	µA	
	@ 105°C	—	12.0	20.00	µA	
I_{DD_VLLS3}	Very low-leakage stop mode 3 current at 3.0 V					
	@ -40°C to 25°C	—	1.8	2.10	µA	

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	@ 70°C	—	4.3	5.70	µA	
	@ 85°C	—	6.6	8.10	µA	
	@ 105°C	—	10.0	17.00	µA	
I_{DD_VLLS2}	Very low-leakage stop mode 2 current at 3.0 V					
	@ -40°C to 25°C	—	1.6	1.80	µA	
	@ 70°C	—	3.1	3.90	µA	
	@ 85°C	—	4.7	7.00	µA	
	@ 105°C	—	6.8	10.90	µA	
I_{DD_VLLS1}	Very low-leakage stop mode 1 current at 3.0 V					
	@ -40°C to 25°C	—	0.70	0.90	µA	
	@ 70°C	—	1.78	2.09	µA	
	@ 85°C	—	2.8	3.25	µA	
	@ 105°C	—	4.0	6.15	µA	
I_{DD_VLLS0}	Very low-leakage stop mode 0 current at 3.0 V with POR detect circuit enabled					
	@ -40°C to 25°C	—	0.40	0.49	µA	
	@ 70°C	—	1.38	1.49	µA	
	@ 85°C	—	2.40	2.70	µA	
	@ 105°C	—	3.6	5.65	µA	
I_{DD_VLLS0}	Very low-leakage stop mode 0 current at 3.0 V with POR detect circuit disabled					
	@ -40°C to 25°C	—	0.12	0.19	µA	
	@ 70°C	—	1.05	1.13	µA	
	@ 85°C	—	2.1	2.45	µA	
	@ 105°C	—	3.3	5.35	µA	
I_{DD_VBAT}	Average current with RTC and 32kHz disabled at 3.0 V					
	@ -40°C to 25°C	—	0.18	0.21	µA	
	@ 70°C	—	0.66	0.86	µA	
	@ 85°C	—	1.52	2.24	µA	
	@ 105°C	—	2.92	4.30	µA	
I_{DD_VBAT}	Average current when CPU is not accessing RTC registers					
	@ 1.8V					
	• @ -40°C to 25°C	—	0.57	0.67	µA	16
	• @ 70°C	—	0.90	1.2	µA	
	• @ 85°C	—	0.90	1.2	µA	
	• @ 105°C	—	2.4	3.5	µA	
	@ 3.0V					

Table continues on the next page...

2.2.5.1 Diagram: Typical IDD_RUN operating behavior

The following data was measured under these conditions:

- MCG in FBE mode for 50 MHz and lower frequencies. MCG in FEE mode at frequencies between 50 MHz and 100MHz.
- No GPIOs toggled
- Code execution from flash with cache enabled
- For the ALLOFF curve, all peripheral clocks are disabled except FTFA

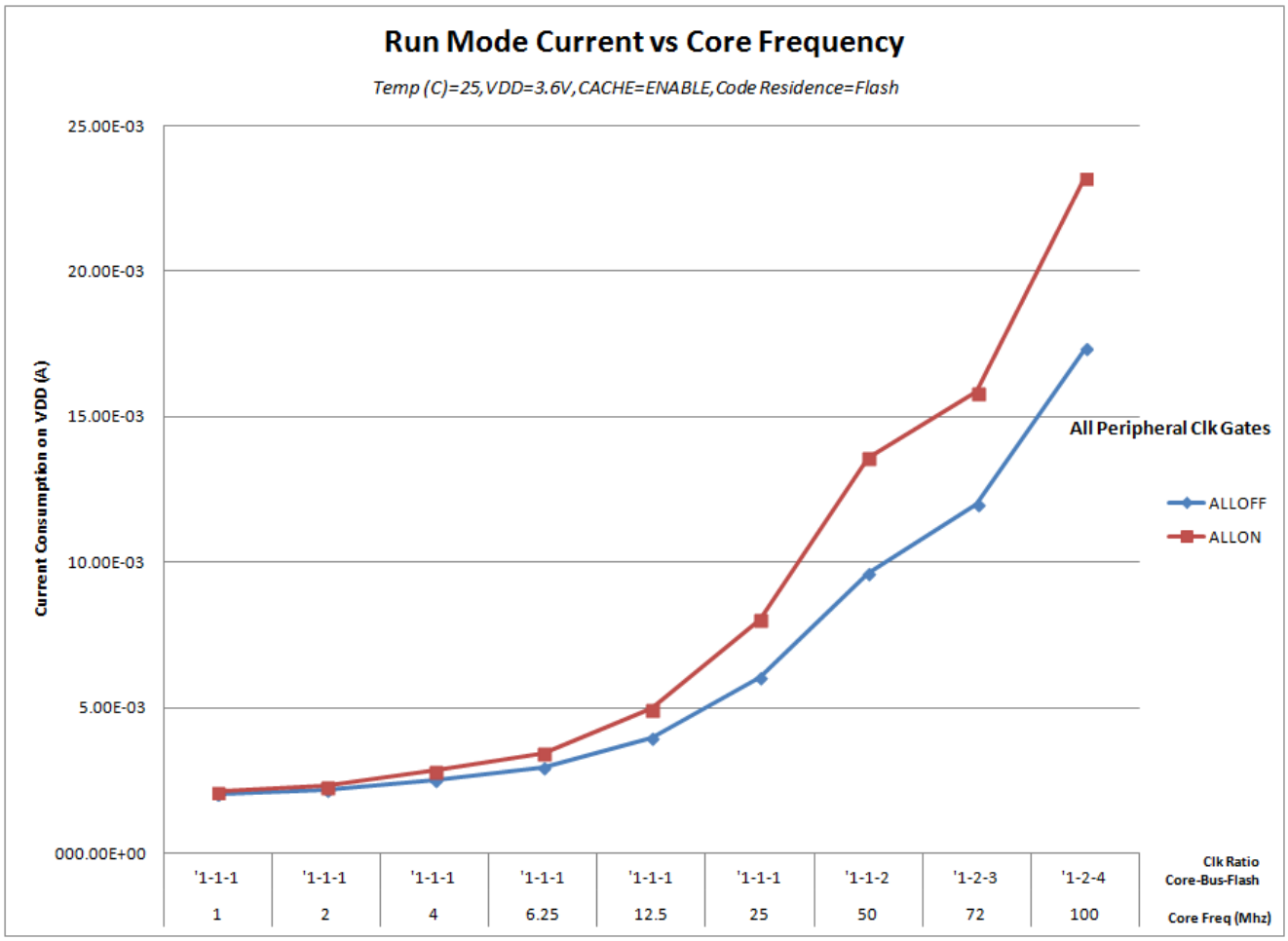

Figure 3. Run mode supply current vs. core frequency

2.4 Thermal specifications

2.4.1 Thermal operating requirements

Table 12. Thermal operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
T_J	Die junction temperature	–40	125	°C	
T_A	Ambient temperature	–40	105	°C	1

1. Maximum T_A can be exceeded only if the user ensures that T_J does not exceed maximum T_J. The simplest method to determine T_J is: $T_J = T_A + R_{\Theta JA} \times$ chip power dissipation.

2.4.2 Thermal attributes

Board type	Symbol	Description	121 XFBGA	100 LQFP	64 LQFP	64 MAPBGA	Unit	Notes
Single-layer (1s)	$R_{\theta JA}$	Thermal resistance, junction to ambient (natural convection)	46.6	63	69	53.8	°C/W	1
Four-layer (2s2p)	$R_{\theta JA}$	Thermal resistance, junction to ambient (natural convection)	39.3	50	51	46.0	°C/W	2
Single-layer (1s)	$R_{\theta JMA}$	Thermal resistance, junction to ambient (200 ft./min. air speed)	39.0	53	57	45.8	°C/W	3
Four-layer (2s2p)	$R_{\theta JMA}$	Thermal resistance, junction to ambient (200 ft./min. air speed)	35.3	44	44	41.0	°C/W	3
—	$R_{\theta JB}$	Thermal resistance, junction to board	36.7	36	33	43.4	°C/W	4

Table continues on the next page...

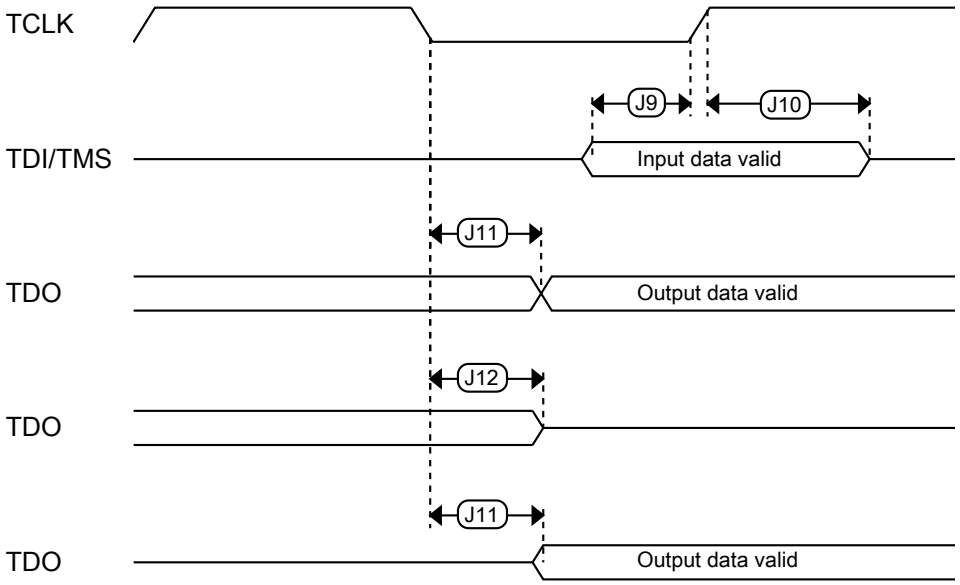

Figure 9. Test Access Port timing

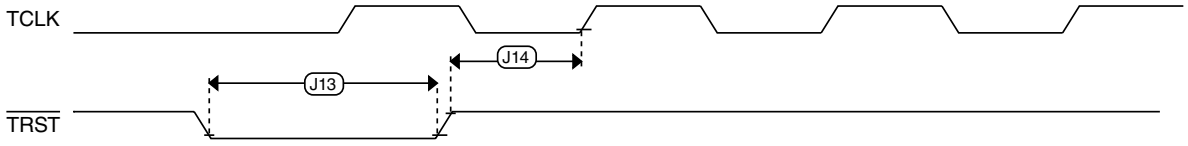

Figure 10. $\overline{\text{TRST}}$ timing

3.2 System modules

There are no specifications necessary for the device's system modules.

3.3 Clock modules

Table 18. Oscillator DC electrical specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
C_y	XTAL load capacitance	—	—	—		2, 3
R_F	Feedback resistor — low-frequency, low-power mode (HGO=0)	—	—	—	MΩ	2, 4
	Feedback resistor — low-frequency, high-gain mode (HGO=1)	—	10	—	MΩ	
	Feedback resistor — high-frequency, low-power mode (HGO=0)	—	—	—	MΩ	
	Feedback resistor — high-frequency, high-gain mode (HGO=1)	—	1	—	MΩ	
R_S	Series resistor — low-frequency, low-power mode (HGO=0)	—	—	—	kΩ	
	Series resistor — low-frequency, high-gain mode (HGO=1)	—	200	—	kΩ	
	Series resistor — high-frequency, low-power mode (HGO=0)	—	—	—	kΩ	
	Series resistor — high-frequency, high-gain mode (HGO=1)	—	0	—	kΩ	
V_{pp}[5]	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, high-gain mode (HGO=1)	—	V_{DD}	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, high-gain mode (HGO=1)	—	V_{DD}	—	V	

1. V_{DD}=3.3 V, Temperature =25 °C
2. See crystal or resonator manufacturer's recommendation
3. C_x and C_y can be provided by using either integrated capacitors or external components.
4. When low-power mode is selected, R_F is integrated and must not be attached externally.
5. The EXTAL and XTAL pins should only be connected to required oscillator components and must not be connected to any other device.

3.3.3.2 Oscillator frequency specifications

Table 19. Oscillator frequency specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
f_{osc_lo}	Oscillator crystal or resonator frequency — low-frequency mode (MCG_C2[RANGE]=00)	32	—	40	kHz	

Table continues on the next page...

3.3.4.2 32 kHz oscillator frequency specifications

Table 21. 32 kHz oscillator frequency specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
f_{osc_lo}	Oscillator crystal	—	32.768	—	kHz	
t_{start}	Crystal start-up time	—	1000	—	ms	1
$f_{ec\_extal32}$	Externally provided input clock frequency	—	32.768	—	kHz	2
$v_{ec\_extal32}$	Externally provided input clock amplitude	700	—	V_{BAT}	mV	2, 3

1. Proper PC board layout procedures must be followed to achieve specifications.
2. This specification is for an externally supplied clock driven to EXTAL32 and does not apply to any other clock input. The oscillator remains enabled and XTAL32 must be left unconnected.
3. The parameter specified is a peak-to-peak value and V_{IH} and V_{IL} specifications do not apply. The voltage of the applied clock must be within the range of V_{SS} to V_{BAT}.

3.4 Memories and memory interfaces

3.4.1 Flash electrical specifications

This section describes the electrical characteristics of the flash memory module.

3.4.1.1 Flash timing specifications — program and erase

The following specifications represent the amount of time the internal charge pumps are active and do not include command overhead.

Table 22. NVM program/erase timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t_{hvpgm4}	Longword Program high-voltage time	—	7.5	18	µs	—
$t_{hversscr}$	Sector Erase high-voltage time	—	13	113	ms	1
$t_{hversall}$	Erase All high-voltage time	—	104	904	ms	1

1. Maximum time based on expectations at cycling end-of-life.

3.4.1.2 Flash timing specifications — commands

Table 23. Flash command timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$t_{rd1sec2k}$	Read 1s Section execution time (flash sector)	—	—	60	µs	1
t_{pgmchk}	Program Check execution time	—	—	45	µs	1

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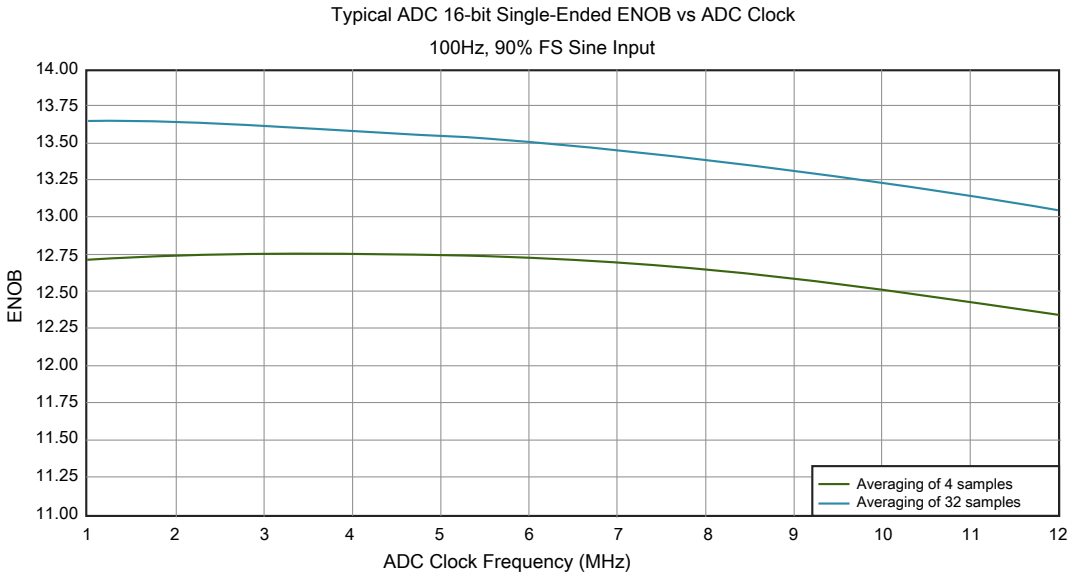

Figure 14. Typical ENOB vs. ADC_CLK for 16-bit single-ended mode

3.6.2 CMP and 6-bit DAC electrical specifications

Table 29. Comparator and 6-bit DAC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit
V_{DD}	Supply voltage	1.71	—	3.6	V
I_{DDHS}	Supply current, High-speed mode (EN=1, PMODE=1)	—	—	200	µA
I_{DDLS}	Supply current, low-speed mode (EN=1, PMODE=0)	—	—	20	µA
V_{AIN}	Analog input voltage	V_{SS} – 0.3	—	V_{DD}	V
V_{AIO}	Analog input offset voltage	—	—	20	mV
V_H	Analog comparator hysteresis[1]				
	• CR0[HYSTCTR] = 00	—	5	—	mV
	• CR0[HYSTCTR] = 01	—	10	—	mV
	• CR0[HYSTCTR] = 10	—	20	—	mV
	• CR0[HYSTCTR] = 11	—	30	—	mV
V_{CMPOh}	Output high	V_{DD} – 0.5	—	—	V
V_{CMPOl}	Output low	—	—	0.5	V
t_{DHS}	Propagation delay, high-speed mode (EN=1, PMODE=1)	20	50	200	ns
t_{DLS}	Propagation delay, low-speed mode (EN=1, PMODE=0)	80	250	600	ns
	Analog comparator initialization delay[2]	—	—	40	µs
I_{DAC6b}	6-bit DAC current adder (enabled)	—	7	—	µA
INL	6-bit DAC integral non-linearity	–0.5	—	0.5	LSB[3]
DNL	6-bit DAC differential non-linearity	–0.3	—	0.3	LSB

1. Typical hysteresis is measured with input voltage range limited to 0.6 to V_{DD}–0.6 V.
2. Comparator initialization delay is defined as the time between software writes to change control inputs (Writes to CMP_DACCR[DACEN], CMP_DACCR[VRSEL], CMP_DACCR[VOSEL], CMP_MUXCR[PSEL], and CMP_MUXCR[MSEL]) and the comparator output settling to a stable level.
3. 1 LSB = $V_{reference}$/64

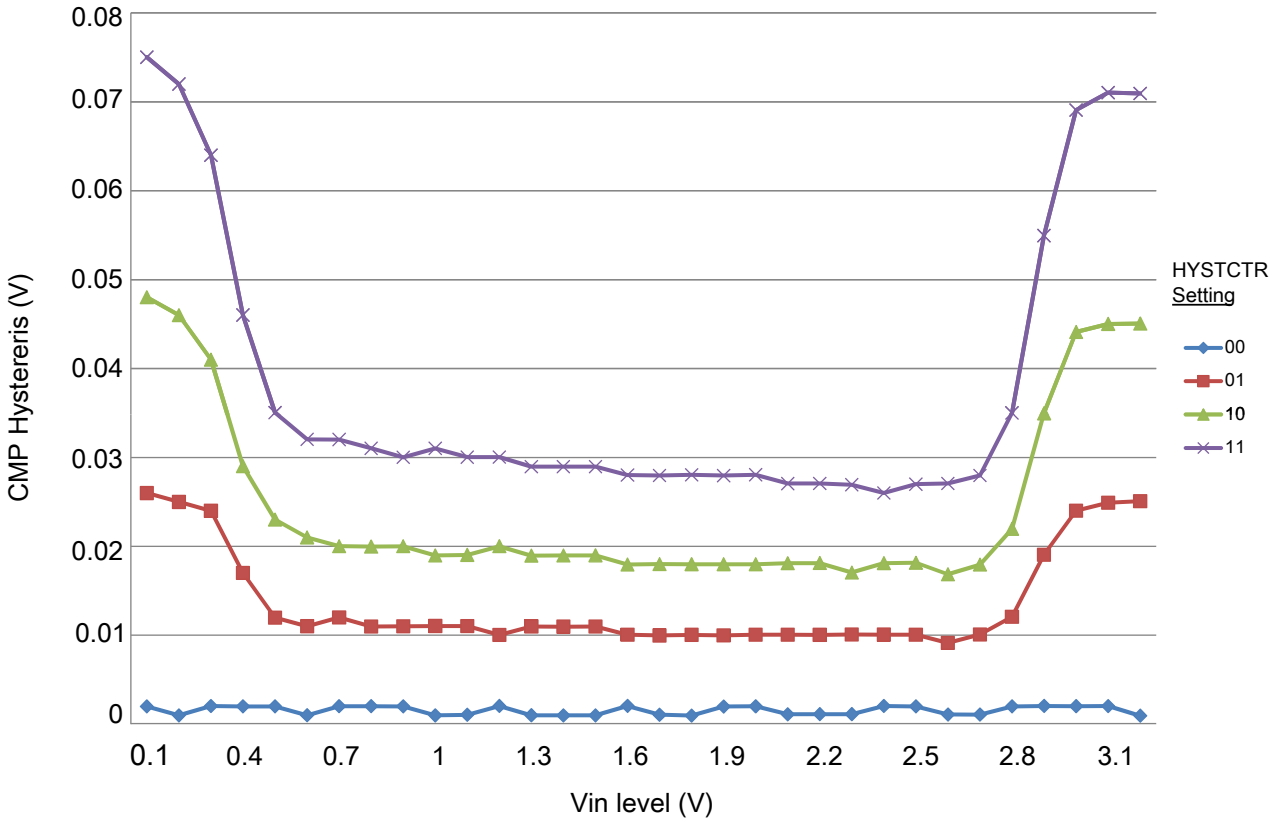

Figure 15. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 0)

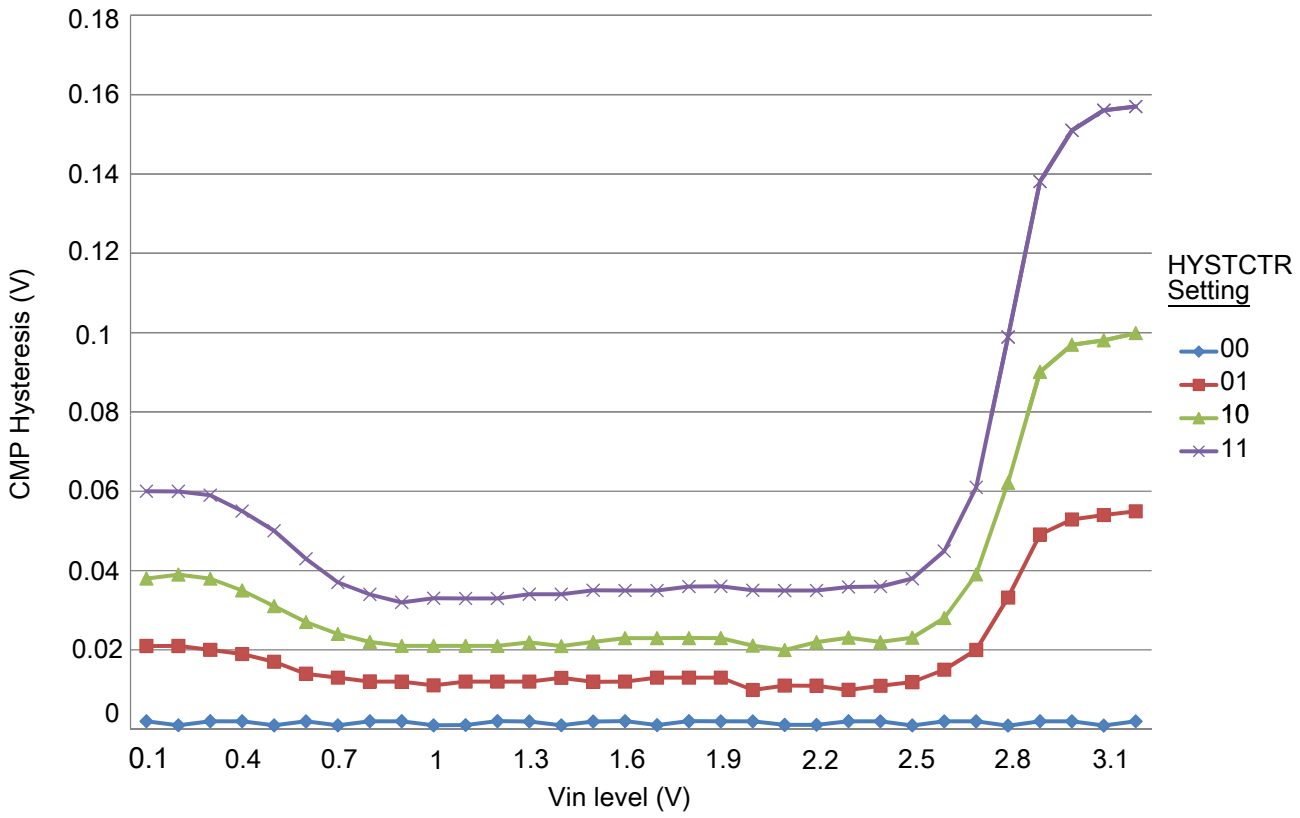

Figure 16. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 1)

3.6.3 12-bit DAC electrical characteristics

3.6.3.1 12-bit DAC operating requirements

Table 30. 12-bit DAC operating requirements

Symbol	Desciption	Min.	Max.	Unit	Notes
V_{DDA}	Supply voltage	1.71	3.6	V	
V_{DACR}	Reference voltage	1.13	3.6	V	1
C_L	Output load capacitance	—	100	pF	2
I_L	Output load current	—	1	mA	

1. The DAC reference can be selected to be V_{DDA} or V_{REFH}.
2. A small load capacitance (47 pF) can improve the bandwidth performance of the DAC.

2. The delay is programmable in SPIx_CTARn[PASC] and SPIx_CTARn[ASC].

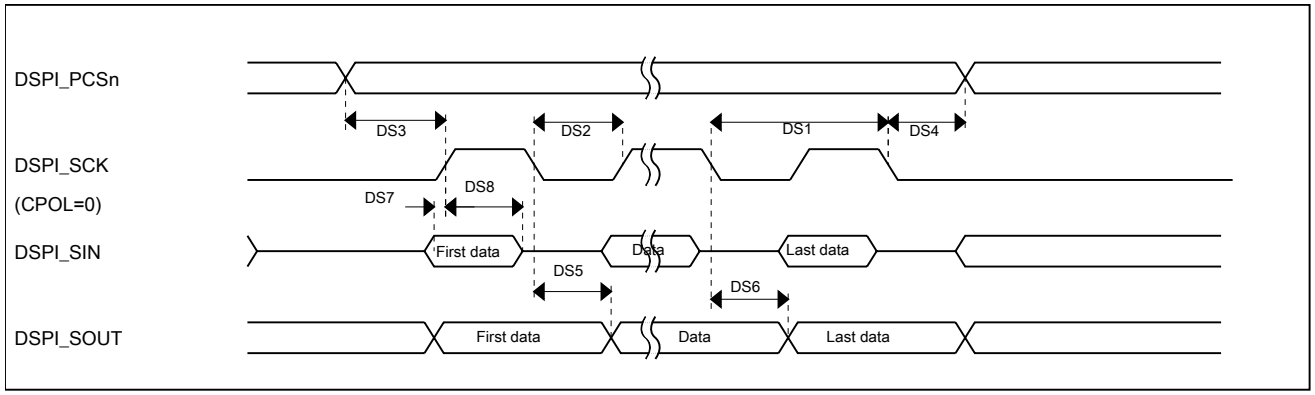

Figure 19. DSPI classic SPI timing — master mode

Table 37. Slave mode DSPI timing (limited voltage range)

Num	Description	Min.	Max.	Unit	Notes
	Operating voltage	2.7	3.6	V	
	Frequency of operation	—	12.5	MHz	1
DS9	DSPI_SCK input cycle time	4 x t_{BUS}	—	ns	
DS10	DSPI_SCK input high/low time	(t_{SCK}/2) – 2	(t_{SCK}/2) + 2	ns	
DS11	DSPI_SCK to DSPI_SOUT valid	—	21.4	ns	
DS12	DSPI_SCK to DSPI_SOUT invalid	0	—	ns	
DS13	DSPI_SIN to DSPI_SCK input setup	2.6	—	ns	
DS14	DSPI_SCK to DSPI_SIN input hold	7	—	ns	
DS15	$\overline{\text{DSPI\_SS}}$ active to DSPI_SOUT driven	—	17	ns	
DS16	$\overline{\text{DSPI\_SS}}$ inactive to DSPI_SOUT not driven	—	17	ns	

1. The maximum operating frequency is measured with noncontinuous CS and SCK. When DSPI is configured with continuous CS and SCK, the SPI clock must not be greater than 1/6 of the bus clock. For example, when the bus clock is 60 MHz, the SPI clock must not be greater than 10 MHz.

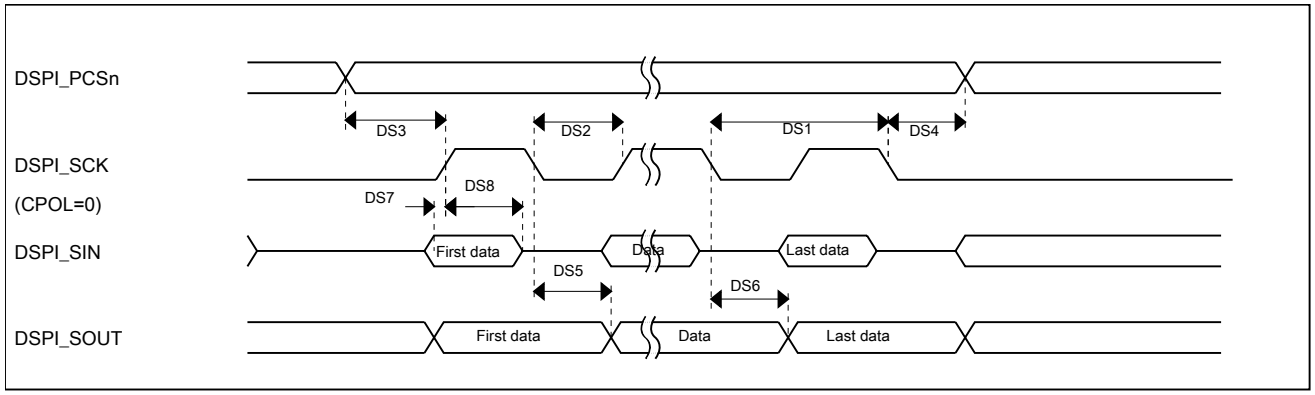

Figure 21. DSPI classic SPI timing — master mode

Table 39. Slave mode DSPI timing (full voltage range)

Num	Description	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
	Frequency of operation	—	6.25	MHz
DS9	DSPI_SCK input cycle time	8 x t_{BUS}	—	ns
DS10	DSPI_SCK input high/low time	(t_{SCK}/2) - 4	($t_{SCK/2)}$ + 4	ns
DS11	DSPI_SCK to DSPI_SOUT valid	—	29.5	ns
DS12	DSPI_SCK to DSPI_SOUT invalid	0	—	ns
DS13	DSPI_SIN to DSPI_SCK input setup	3.2	—	ns
DS14	DSPI_SCK to DSPI_SIN input hold	7	—	ns
DS15	$\overline{\text{DSPI\_SS}}$ active to DSPI_SOUT driven	—	25	ns
DS16	$\overline{\text{DSPI\_SS}}$ inactive to DSPI_SOUT not driven	—	25	ns

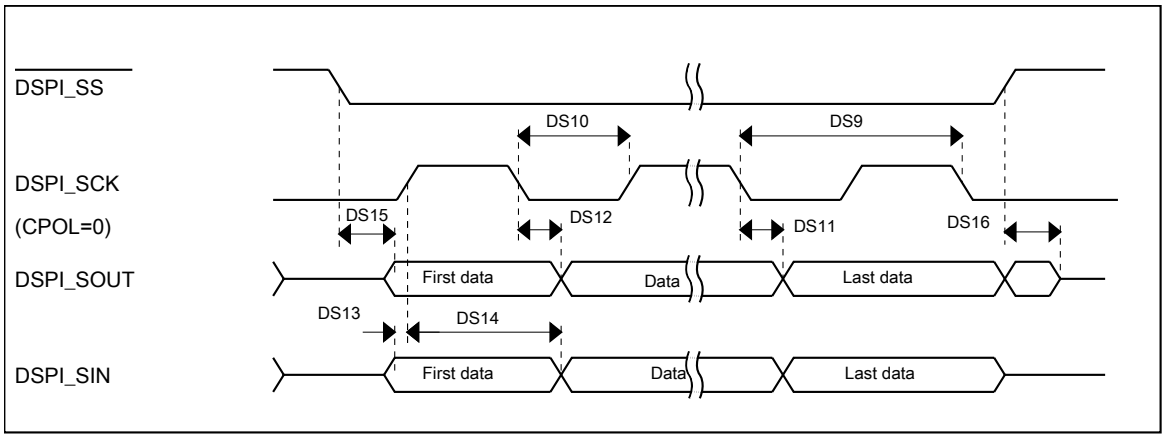

Figure 22. DSPI classic SPI timing — slave mode

Table 45. I2S/SAI slave mode timing in Normal Run, Wait and Stop modes (full voltage range) (continued)

Num.	Characteristic	Min.	Max.	Unit
S12	I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low (input)	45%	55%	MCLK period
S13	I2S_TX_FS/I2S_RX_FS input setup before I2S_TX_BCLK/I2S_RX_BCLK	5.8	—	ns
S14	I2S_TX_FS/I2S_RX_FS input hold after I2S_TX_BCLK/I2S_RX_BCLK	2	—	ns
S15	I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output valid	—	28.5	ns
S16	I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output invalid	0	—	ns
S17	I2S_RXD setup before I2S_RX_BCLK	5.8	—	ns
S18	I2S_RXD hold after I2S_RX_BCLK	2	—	ns
S19	I2S_TX_FS input assertion to I2S_TXD output valid[1]	—	26.3	ns

1. Applies to first bit in each frame and only if the TCR4[FSE] bit is clear

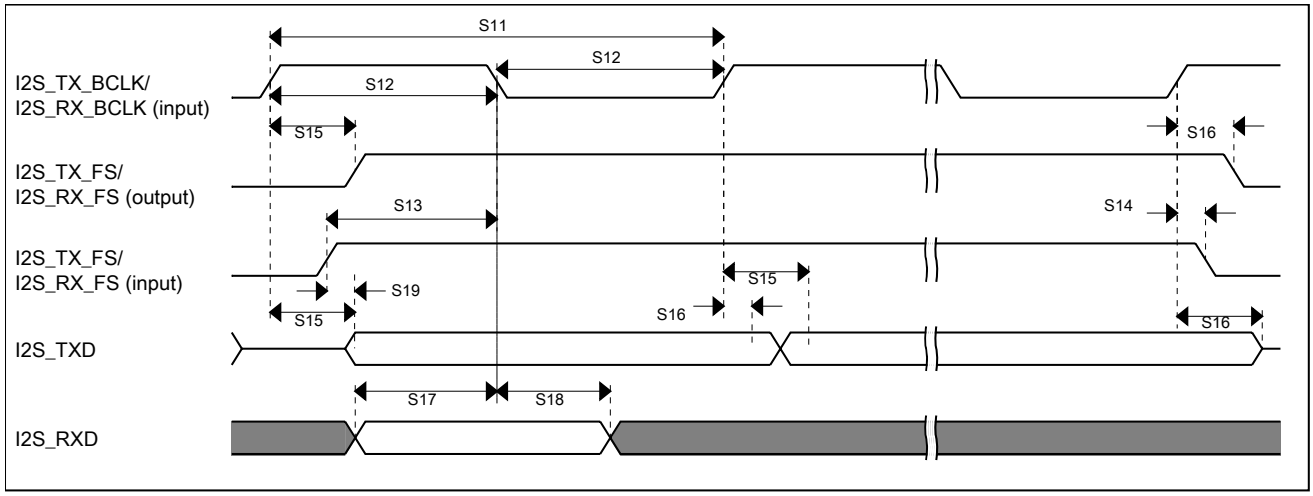

Figure 27. I2S/SAI timing — slave modes

3.8.6.3 VLPR, VLPW, and VLPS mode performance over the full operating voltage range

This section provides the operating performance over the full operating voltage for the device in VLPR, VLPW, and VLPS modes.

Table 46. I2S/SAI master mode timing in VLPR, VLPW, and VLPS modes (full voltage range)

Num.	Characteristic	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V

Table continues on the next page...

121 BGA	100 LQFP	64 LQFP	64 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
G10	54	36	F6	PTB1	ADC0_ SE9/ ADC1_SE9	ADC0_ SE9/ ADC1_SE9	PTB1	I2C0_SDA	FTM1_CH1			FTM1_QD_ PHB		
G9	55	37	E7	PTB2	ADC0_ SE12	ADC0_ SE12	PTB2	I2C0_SCL	UART0_ RTS_b			FTM0_ FLT3		
G8	56	38	E8	PTB3	ADC0_ SE13	ADC0_ SE13	PTB3	I2C0_SDA	UART0_ CTS_b			FTM0_ FLT0		
D11	—	—	—	PTB8	DISABLED		PTB8		LPUART0_ RTS_b					
E10	57	—	—	PTB9	DISABLED		PTB9	SPI1_ PCS1	LPUART0_ CTS_b					
D10	58	—	—	PTB10	ADC1_ SE14	ADC1_ SE14	PTB10	SPI1_ PCS0	LPUART0_ RX			FTM0_ FLT1		
C10	59	—	—	PTB11	ADC1_ SE15	ADC1_ SE15	PTB11	SPI1_SCK	LPUART0_ TX			FTM0_ FLT2		
—	60	—	—	VSS	VSS	VSS								
—	61	—	—	VDD	VDD	VDD								
B10	62	39	E6	PTB16	DISABLED		PTB16	SPI1_ SOUT	UART0_RX	FTM_ CLKIN0		EWM_IN		
E9	63	40	D7	PTB17	DISABLED		PTB17	SPI1_SIN	UART0_TX	FTM_ CLKIN1		EWM_ OUT_b		
D9	64	41	D6	PTB18	DISABLED		PTB18		FTM2_CH0	I2S0_TX_ BCLK		FTM2_QD_ PHA		
C9	65	42	C7	PTB19	DISABLED		PTB19		FTM2_CH1	I2S0_TX_ FS		FTM2_QD_ PHB		
F10	66	—	—	PTB20	DISABLED		PTB20					CMP0_ OUT		
F9	67	—	—	PTB21	DISABLED		PTB21					CMP1_ OUT		
F8	68	—	—	PTB22	DISABLED		PTB22							
E8	69	—	—	PTB23	DISABLED		PTB23		SPI0_ PCS5					
B9	70	43	D8	PTC0	ADC0_ SE14	ADC0_ SE14	PTC0	SPI0_ PCS4	PDB0_ EXTRG	USB_SOF_ OUT				
D8	71	44	C6	PTC1/ LLWU_P6	ADC0_ SE15	ADC0_ SE15	PTC1/ LLWU_P6	SPI0_ PCS3	UART1_ RTS_b	FTM0_CH0		I2S0_TXD0	LPUART0_ RTS_b	
C8	72	45	B7	PTC2	ADC0_ SE4b/ CMP1_IN0	ADC0_ SE4b/ CMP1_IN0	PTC2	SPI0_ PCS2	UART1_ CTS_b	FTM0_CH1		I2S0_TX_ FS	LPUART0_ CTS_b	
B8	73	46	C8	PTC3/ LLWU_P7	CMP1_IN1	CMP1_IN1	PTC3/ LLWU_P7	SPI0_ PCS1	UART1_RX	FTM0_CH2	CLKOUT	I2S0_TX_ BCLK	LPUART0_ RX	
—	74	47	E3	VSS	VSS	VSS								
—	75	48	E4	VDD	VDD	VDD								
A8	76	49	B8	PTC4/ LLWU_P8	DISABLED		PTC4/ LLWU_P8	SPI0_ PCS0	UART1_TX	FTM0_CH3		CMP1_ OUT	LPUART0_ TX	

121 BGA	100 LQFP	64 LQFP	64 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
D7	77	50	A8	PTC5/ LLWU_P9	DISABLED		PTC5/ LLWU_P9	SPI0_SCK	LPTMR0_ ALT2	I2S0_RXD0		CMP0_ OUT	FTM0_CH2	
C7	78	51	A7	PTC6/ LLWU_P10	CMP0_IN0	CMP0_IN0	PTC6/ LLWU_P10	SPI0_ SOUT	PDB0_ EXTRG	I2S0_RX_ BCLK		I2S0_ MCLK		
B7	79	52	B6	PTC7	CMP0_IN1	CMP0_IN1	PTC7	SPI0_SIN	USB_SOF_ OUT	I2S0_RX_ FS				
A7	80	53	A6	PTC8	ADC1_ SE4b/ CMP0_IN2	ADC1_ SE4b/ CMP0_IN2	PTC8			I2S0_ MCLK				
D6	81	54	B5	PTC9	ADC1_ SE5b/ CMP0_IN3	ADC1_ SE5b/ CMP0_IN3	PTC9			I2S0_RX_ BCLK		FTM2_ FLT0		
C6	82	55	B4	PTC10	ADC1_ SE6b	ADC1_ SE6b	PTC10	I2C1_SCL		I2S0_RX_ FS				
C5	83	56	A5	PTC11/ LLWU_P11	ADC1_ SE7b	ADC1_ SE7b	PTC11/ LLWU_P11	I2C1_SDA						
B6	84	—	—	PTC12	DISABLED		PTC12							
A6	85	—	—	PTC13	DISABLED		PTC13							
A5	86	—	—	PTC14	DISABLED		PTC14							
B5	87	—	—	PTC15	DISABLED		PTC15							
F7	88	—	—	VSS	VSS	VSS								
E7	89	—	—	VDD	VDD	VDD								
D5	90	—	—	PTC16	DISABLED		PTC16		LPUART0_ RX					
C4	91	—	—	PTC17	DISABLED		PTC17		LPUART0_ TX					
B4	92	—	—	PTC18	DISABLED		PTC18		LPUART0_ RTS_b					
D4	93	57	C3	PTD0/ LLWU_P12	DISABLED		PTD0/ LLWU_P12	SPI0_ PCS0	UART2_ RTS_b			LPUART0_ RTS_b		
D3	94	58	A4	PTD1	ADC0_ SE5b	ADC0_ SE5b	PTD1	SPI0_SCK	UART2_ CTS_b			LPUART0_ CTS_b		
C3	95	59	C2	PTD2/ LLWU_P13	DISABLED		PTD2/ LLWU_P13	SPI0_ SOUT	UART2_RX			LPUART0_ RX	I2C0_SCL	
B3	96	60	B3	PTD3	DISABLED		PTD3	SPI0_SIN	UART2_TX			LPUART0_ TX	I2C0_SDA	
A3	97	61	A3	PTD4/ LLWU_P14	DISABLED		PTD4/ LLWU_P14	SPI0_ PCS1	UART0_ RTS_b	FTM0_CH4		EWM_IN	SPI1_ PCS0	
A2	98	62	C1	PTD5	ADC0_ SE6b	ADC0_ SE6b	PTD5	SPI0_ PCS2	UART0_ CTS_b	FTM0_CH5		EWM_ OUT_b	SPI1_SCK	
B2	99	63	B2	PTD6/ LLWU_P15	ADC0_ SE7b	ADC0_ SE7b	PTD6/ LLWU_P15	SPI0_ PCS3	UART0_RX	FTM0_CH6		FTM0_ FLT0	SPI1_ SOUT	
A1	100	64	A2	PTD7	DISABLED		PTD7		UART0_TX	FTM0_CH7		FTM0_ FLT1	SPI1_SIN	
A11	—	—	—	NC	NC	NC								

121 BGA	100 LQFP	64 LQFP	64 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
K3	—	—	—	NC	NC	NC								
H4	—	—	—	NC	NC	NC								
B11	—	—	—	NC	NC	NC								
C11	—	—	—	NC	NC	NC								
H11	—	—	—	NC	NC	NC								
C1	—	—	—	NC	NC	NC								
D2	—	—	—	NC	NC	NC								
D1	—	—	—	NC	NC	NC								
E1	—	—	—	NC	NC	NC								
J3	—	—	—	NC	NC	NC								
H3	—	—	—	NC	NC	NC								
J9	—	—	—	NC	NC	NC								
J4	—	—	—	NC	NC	NC								
A10	—	—	—	NC	NC	NC								
A9	—	—	—	NC	NC	NC								
B1	—	—	—	NC	NC	NC								
C2	—	—	—	NC	NC	NC								
L7	—	—	—	NC	NC	NC								
F11	—	—	—	NC	NC	NC								
E11	—	—	—	NC	NC	NC								
A4	—	—	—	NC	NC	NC								

5.2 Recommended connection for unused analog and digital pins

The following table shows the recommended connections for analog interface pins if those analog interfaces are not used in the customer's application.

Table 48. Recommended connection for unused analog interfaces

Pin Type		Short recommendation	Detailed recommendation
Analog/non GPIO	PGAx/ADCx	Float	Analog input - Float
Analog/non GPIO	ADCx/CMPx	Float	Analog input - Float
Analog/non GPIO	VREF_OUT	Float	Analog output - Float
Analog/non GPIO	DACx_OUT	Float	Analog output - Float
Analog/non GPIO	RTC_WAKEUP_B	Float	Analog output - Float
Analog/non GPIO	XTAL32	Float	Analog output - Float
Analog/non GPIO	EXTAL32	Float	Analog input - Float

Table continues on the next page...

Table 48. Recommended connection for unused analog interfaces (continued)

Pin Type		Short recommendation	Detailed recommendation
GPIO/Analog	PTA18/EXTAL0	Float	Analog input - Float
GPIO/Analog	PTA19/XTAL0	Float	Analog output - Float
GPIO/Analog	PTx/ADCx	Float	Float (default is analog input)
GPIO/Analog	PTx/CMPx	Float	Float (default is analog input)
GPIO/Digital	PTA0/JTAG_TCLK	Float	Float (default is JTAG with pulldown)
GPIO/Digital	PTA1/JTAG_TDI	Float	Float (default is JTAG with pullup)
GPIO/Digital	PTA2/JTAG_TDO	Float	Float (default is JTAG with pullup)
GPIO/Digital	PTA3/JTAG_TMS	Float	Float (default is JTAG with pullup)
GPIO/Digital	PTA4/NMI_b	10kΩ pullup or disable and float	Pull high or disable in PCR & FOPT and float
GPIO/Digital	PTx	Float	Float (default is disabled)
USB	USB0_DP	Float	Float
USB	USB0_DM	Float	Float
USB	USBVDD	Tie to ground through 10kΩ	Tie to ground through 10kΩ
VBAT	VBAT	Float	Float
VDDA	VDDA	Always connect to VDD potential	Always connect to VDD potential
VREFH	VREFH	Always connect to VDD potential	Always connect to VDD potential
VREFL	VREFL	Always connect to VSS potential	Always connect to VSS potential
VSSA	VSSA	Always connect to VSS potential	Always connect to VSS potential

5.3 K22 Pinouts

This figure shows the pinout diagram for the devices supported by this document. Many signals may be multiplexed onto a single pin. To determine what signals can be used on which pin, see the previous section.

Table 51. Revision History

Rev. No.	Date	Substantial Changes
7	08/2016	• Added Terminology and Guidelines section • Updated the front matter section • Added Device Revision Number Table • Updated Chip Errata naming convention in Related Resource table
6	10/2015	• In "Power consumption operating behaviors" section, added "Low power mode peripheral adders—typical value" table • In "Thermal operating requirements" table, in footnote, corrected "$T_J = T_A + \Theta_{JA}$" to "$T_J = T_A + R_{\Theta JA}$" • Updated "IRC48M specifications" table • Updated "NVM program/erase timing specifications" table; updated values for $t_{hversall}$ (Erase All high-voltage time) • In "Slave mode DSPI timing (limited voltage range)" table, added footnote regarding maximum frequency of operation • Added new section, "Recommended connections for unused analog and digital pins"

5	4/2015	• On page 1:
		  • In first bullet of introduction, updated power consumption data to align with the data in the "Power consumption operating behaviors" table
		  • In second bullet of introduction, added "USB FS device crystal-less functionality"
		  • Under "Communication interfaces," updated I^2C bullet to indicate support for up to 1 Mbps operation
		  • Under "Operating characteristics," specified that voltage range includes flash writes
		• In "Voltage and current operating requirements" table:
		  • Removed content related to positive injection
		  • Updated footnote 1 to say that all analog and I/O pins are internally clamped to V_{SS} only (not V_{SS} and V_{DD})through ESD protection diodes.
		• In"Power consumption operating behaviors" table:
		  • Added additional temperature data in power consumption table
		  • Added Max IDD values based on characterization results equivalent to mean + 3 sigma
		• Updated "EMC radiated emissions operating behaviors" table
		• In "Thermal operating requirements" table, added the following footnote for ambient temperature: "Maximum T_A can be exceeded only if the user ensures that T_J does not exceed maximum T_J. The simplest method to determine T_J is: $T_J = T_A + \Theta_{JA}$ x chip power dissipation"
		• Updated "IRC48M Specifications":
		  • Updated maximum values for $\Delta_{firc48m\_ol\_lv}$ and $\Delta_{firc48m\_ol\_hv}$ (full temperature)
		  • Added specifications for $\Delta_{firc48m\_ol\_hv}$ (-40°C to 85°C)
		• Updated notes in "USB electrical specifications" section
		• In "I^2C timing" table,
		  • Added the following footnote on maximum Fast mode value for SCL Clock Frequency: "The maximum SCL Clock Frequency in Fast mode with maximum bus loading can only be achieved when using the High drive pins across the full voltage range and when using the Normal drive pins and VDD ≥ 2.7 V."
		  • Updated minimum Fast mode value for LOW period of the SCL clock to 1.25 µ
		• Added "I^2C 1 Mbps timing" table
		• Specified that the figure, "K22F 64 LQFP Pinout Diagram" is a top view
		• Specified that the figure, "K22F 64 MAPBGA Pinout Diagram" is a transparent top view
		• Specified that the figure, "K22F 100 LQFP Pinout Diagram" is a top view

Table continues on the next page...